Multiplexers and Signal Switches
Glossary

Application Report
This glossary provides a brief overview and introduction to the terminology, features, and parameters for multiplexers and signal switches. The entire switches and multiplexers portfolio can be found at www.ti.com switches.

For components used to manage power rails, TI offers a power switch and power multiplexer portfolio which can each be found at www.ti.com/powerswitch.
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   - Output-to-output skew ($t_{SK}$)
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Signal switch — An integrated circuit (IC) used for connecting and disconnecting an electrical circuit. For more information, see the *Switches and muxes: What are switches & multiplexers?* training video from TI Precision Labs.

![Figure 1-1. Ideal 1:1 SPST Switch](image)

Multiplexer (Mux) — An integrated circuit that connects a selected signal path to a single line.

![Figure 1-2. Ideal 4:1 Mux](image)

Analog switches and multiplexers — These devices are used for switching and multiplexing analog and digital signals up to 500 mA in applications such as:

- Precision data acquisition
- GPIO expansion and diagnostics
- System communication and bus isolation
- System protection and power sequencing
- General-purpose signal switching

Protocol-specific switches and multiplexers — These devices are defined to support specific protocol applications such as USB, HDMI, LAN, MIPI, audio, memory and so forth.

Power multiplexer — These devices are a set of electronic switches used to select and transition between two or more input power paths to a single output.

Power switch — These devices manage power distribution for paths typically greater than 500 mA between a voltage source to a load. They can be used to limit inrush current, enable power sequencing, provide protection from overvoltage or overcurrent events, and more.

Precision — These devices minimize offset error and signal distortion in a high-accuracy measurement system.

Protection — These devices isolate I/O signal paths and protect the system using powered-off, overvoltage and undershoot protection.

Low voltage — These devices support I/O signals ≤ ±24 V

Mid voltage — These devices support I/O signals > ±24 V

Configuration — Defines the number of signals that can be selected. Table 1-1 shows the typical configurations.

Channel — Defines the number of configurations (circuits) in a single device. Table 1-1 shows the 1- and 2- channel configurations, but the number of channels may exceed 2.
### Table 1-1. Configurations and Channels

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<thead>
<tr>
<th>Configuration</th>
<th>1-Channel</th>
<th>2-Channel</th>
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**Table 1-1. Configurations and Channels (continued)**

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Absolute maximum ratings — These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under the Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. Stresses beyond those listed under the Absolute Maximum Rating may cause permanent damage to the device.

Recommended operating conditions — The operating conditions for which the device has been characterized.

Single power supply — Device with only positive power supply pins with reference to ground. The voltage applied is labeled as $V_{DD}$, $V_{CC}$, $V_{+}$ and so forth.

Dual power supply — Device with positive and negative supply pins with reference to ground. Voltage applied at the positive pin is labeled as $V_{DD}$, $V_{CC}$, $V_{+}$, and so forth, and at the negative pin is labeled as $V_{SS}$, $V_{EE}$, $V_{-}$, and so forth.

Switch control signal levels ($V_{IH}$, $V_{IL}$) — Voltage levels required on the control pins (EN, SEL, IN, and so forth) required for the switch to change the internal signal path.

- $V_{IH}$ — The minimum voltage for the input control signal to achieve a logic "1" high value
- $V_{IL}$ — The maximum voltage for the input control signal to remain a logic "0" low value

Rail-to-rail — A common term meaning that a device will support $V_{IO}$ voltage range between the most positive and most negative power supply rails.
**Input/Output voltage beyond supply** – The switch can support voltage range beyond the supply rail to \( V_{I/O(MAX)} \) as indicated by the recommended operating conditions.

![Figure 2-4. I/O Voltage Beyond Supply](image)

**Bidirectional signal path** – The switch conducts equally well from source (S) to drain (D) or from drain (D) to source (S). Each channel has very similar characteristics in both directions and supports both analog and digital signals. TI analog switches and multiplexers are typically bidirectional. See the *Switches and muxes: Are switches & multiplexers bidirectional?* training video from *TI Precision Labs*.

![Figure 2-5. Bidirectional Signal Path](image)
1.8-V control logic – Switches with this feature have a built-in voltage translator to prevent voltage mismatch between the supply rail and the control logic. $V_{IH}$ and $V_{IL}$ levels are compatible with the 1.8-V logic levels at any voltage supply. See the Simplifying Design With 1.8 V logic MUXes and Switches Tech Note for more information.

Fail-safe logic – Ensures the switch stays off and the voltage on the logic pin ($V_{SEL}$) does not back-power $V_{DD}$ when $V_{SEL}$ is greater than $V_{DD}$. See the Switches and muxes: What is fail-safe logic? training video from TI Precision Labs.

Injection current control — Allows signals on disabled (high-Z) signal paths to exceed the supply voltage without affecting the signal of the enabled signal path. For example, if current is injected into a disabled signal path, raising the voltage at the pin above the supply, the signal on the enabled signal path will not be affected. See the Switches and muxes: Prevent crosstalk with injection current control training video from TI Precision Labs.
Integrated pulldown resistor on logic pin – Internal weak pulldown resistors to GND to ensure the logic pins are not floating.

**Figure 3-3. Integrated Pulldown Resistor on Logic Pin**

Latch-up immunity – Devices that are latch-up immune are built in a Silicon On Insulator (SOI) process and will not latch-up when exposed to current injection or overvoltage events. See the *Switches and muxes: What is latch-up immunity?* training video from TI Precision Labs.

**Figure 3-4. Latch-Up Immunity With SOI Process**

Overvoltage protection – When the input voltage $V_{I/O}$ exceeds the defined threshold voltage, $V_{TH}$, the switch enters the high impedance state, isolates signal path, and protects downstream components.

**Figure 3-5. Overvoltage Protection**
**Powered-off protection** – Protects switch and isolates signal path when signals are present at the I/O pins and VDD = 0 V. See the *Switches and muxes: Simplify power sequencing with powered-off protection* training video from Ti Precision Labs and the *Eliminate Power Sequencing With Powered-off Protection Signal Switches Tech Note* for more information.

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**Figure 3-6. Powered-Off Protection**

![Diagram showing powered-off protection](image-url)
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For more parameter information, see the device data sheet.

**On-resistance** ($R_{ON}$) — The resistance inserted into the signal path as a result of the switch path being turned on.

![Figure 4-1. On-Resistance](image)

**On-resistance flatness** ($R_{ON FLAT}$) — Difference between the maximum and minimum value of $R_{ON}$ in a channel over the $V_D$ or $V_S$ voltage range.

![Figure 4-2. On-Resistance Flatness](image)

**OFF leakage current** ($I_{D(OFF)}$, $I_{S(OFF)}$) — Leakage current measured at the input port, with the corresponding channel output in the OFF state under worst-case input and output conditions.

![Figure 4-3. OFF Leakage Current](image)
Powered-off I/O pin leakage current ($I_{POFF}$) — The leakage current flowing into or out of the source pin when the device is powered off ($V_{DD} = 0V$).

ON leakage current ($I_{D(ON)}$, $I_{S(ON)}$) — Leakage current measured at the input port in the ON state, with the corresponding output port in the ON state and the output being open.

Control input leakage ($I_{SEL}$ or $I_{EN}$) — Leakage measured at the switch control pins.
For detailed information of dynamic characteristics, see the *Multiplexers: Bandwidth, Channel-to-Channel Crosstalk, Off-Isolation and THD+Noise* training video from *TI Precision Labs*.

For more parameter information, see the device data sheet.

**Off capacitance source and drain (C\text{OFF})** — The capacitive loading when a switch path is in the high-impedance state.

![Figure 5-1. Source and Drain Off Capacitance](image)

**On capacitance source and drain (C\text{ON})** — The capacitive loading when a switch path is in the low-impedance state.

![Figure 5-2. Source and Drain On Capacitance](image)
Charge injection \( Q_C \) — Charge injection is a measurement of unwanted signal coupling from the control (EN) input to the analog output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input.

\[
Q_C = C_L \cdot \Delta V_D
\]

**Figure 5-3. Charge Injection**

Off-isolation \( O_{DO} \) — A measurement OFF-state switch impedance. This is the ratio of \( V_{D1} \) to \( V_{S1} \) measured in dB at a specific frequency, with the corresponding channel in the OFF state.

\[
O_{DO} = 20 \cdot \log \left( \frac{V_{D1}}{V_{S1}} \right)
\]

**Figure 5-4. Off-Isolation**

Channel-to-channel crosstalk \( X_{TALK} \) — A measurement of unwanted signal coupling from an ON channel to an OFF channel. This is the ratio of \( V_{S2} \) to \( V_{S1} \) measured in dB at a specific frequency.

\[
X_{TALK} = 20 \cdot \log \left( \frac{V_{S2}}{V_{S1}} \right)
\]

**Figure 5-5. Channel-to-Channel Crosstalk**
**Bandwidth (BW)** — The frequency range of signals that can pass through the switch with no more than 3 dB of attenuation.

![Figure 5-6. Bandwidth](image-url)
For detailed information, see the *Switches and muxes: What are timing characteristics?* training video from TI Precision Labs.

For more parameter information, see the device data sheet.

**Transition time ($t_{\text{TRAN}}$)** — The time taken by the switch output to rise or fall within a given percentage of the final value after the address signal has risen or fallen past the logic threshold.

![Transition Time Diagram](image-url)

**Figure 6-1. Transition Time**
Device turn on time from enable pin
($t_{\text{ON(EN)}}$ and $t_{\text{OFF(EN)}}$) — The time taken by the switch output to rise or fall within a given percentage of the final value after the enable has risen or fallen past the logic threshold.

![Device Turn on Time From Enable Pin](image)

Break-before-make time ($t_{\text{OPEN(BBM)}}$) — Ensures that in a multiplexer, two multiplexer paths are never electrically connected when the signal path is changed by the select input.

![Break-Before-Make Time](image)
**Make-before-break time (t\(_{CLOS ED \,(MBB)}\))** — Ensures that in a multiplexer, two multiplexer paths are never electrically disconnected when the signal path is changed by the select input.

**Output-to-output skew (t\(_{SK}\))** — The maximum difference between the propagation delays of different outputs due to different internal paths.
Propagation delay through the switch ($t_{pd}$) — The time required for a signal to pass from the input signal pin to the respective output signal pin.

Figure 6-6. Propagation Delay Through the Switch
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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<td>• Updated the numbering format for tables, figures and cross-references throughout the document</td>
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